

お客様各位

資料中の「ラピステクノロジー」等名称の ローム株式会社への変更

2024 年4 月1 日をもって、ローム株式会社は、100%子会社である ラピステクノロジー株式会社を吸収合併しました。従いまして、本資料中にあります 「ラピステクノロジー株式会社」、「ラピステクノ」、「ラピス」といった表記に関しましては、全て「ローム株式会社」に読み替えて適用するものとさせていただきます。 なお、会社名、会社商標、ロゴ等以外の製品に関する内容については、変更はありません。 以上、ご理解の程よろしくお願いいたします。

2024年4月1日 ローム株式会社



Bluetooth® low energy Module (MK71511/MK71521) Application Note MK71521 Connection distance measurement

Issue Date: Oct. 16, 2020



NOTES

- 1) The information contained herein is subject to change without notice.
- 2) When using LAPIS Technology Products, refer to the latest product information (data sheets, user's manuals, application notes, etc.), and ensure that usage conditions (absolute maximum ratings, recommended operating conditions, etc.) are within the ranges specified. LAPIS Technology disclaims any and all liability for any malfunctions, failure or accident arising out of or in connection with the use of LAPIS Technology Products outside of such usage conditions specified ranges, or without observing precautions. Even if it is used within such usage conditions specified ranges, semiconductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury, fire or the other damage from break down or malfunction of LAPIS Technology Products, please take safety at your own risk measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. You are responsible for evaluating the safety of the final products or systems manufactured by you.
- 3) Descriptions of circuits, software and other related information in this document are provided only to illustrate the standard operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. And the peripheral conditions must be taken into account when designing circuits for mass production. LAPIS Technology disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, and other related information.
- 4) No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of LAPIS Technology or any third party with respect to LAPIS Technology Products or the information contained in this document (including but not limited to, the Product data, drawings, charts, programs, algorithms, and application examples, etc.). Therefore LAPIS Technology shall have no responsibility whatsoever for any dispute, concerning such rights owned by third parties, arising out of the use of such technical information.
- 5) The Products are intended for use in general electronic equipment (AV/OA devices, communication, consumer systems, gaming/entertainment sets, etc.) as well as the applications indicated in this document. For use of our Products in applications requiring a high degree of reliability (as exemplified below), please be sure to contact a LAPIS Technology representative and must obtain written agreement: transportation equipment (cars, ships, trains, etc.), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems, etc. LAPIS Technology disclaims any and all liability for any losses and damages incurred by you or third parties arising by using the Product for purposes not intended by us. Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters, etc.
- 6) The Products specified in this document are not designed to be radiation tolerant.
- 7) LAPIS Technology has used reasonable care to ensure the accuracy of the information contained in this document. However, LAPIS Technology does not warrant that such information is error-free and LAPIS Technology shall have no responsibility for any damages arising from any inaccuracy or misprint of such information.
- 8) Please use the Products in accordance with any applicable environmental laws and regulations, such as the RoHS Directive. LAPIS Technology shall have no responsibility for any damages or losses resulting non-compliance with any applicable laws or regulations.
- 9) When providing our Products and technologies contained in this document to other countries, you must abide by the procedures and provisions stipulated in all applicable export laws and regulations, including without limitation the US Export Administration Regulations and the Foreign Exchange and Foreign Trade Act..
- 10) Please contact a ROHM sales office if you have any questions regarding the information contained in this document or LAPIS Technology's Products.
- 11) This document, in part or in whole, may not be reprinted or reproduced without prior consent of LAPIS Technology.

(Note) "LAPIS Technology" as used in this document means LAPIS Technology Co., Ltd.

Copyright 2020 LAPIS Technology Co., Ltd.

LAPIS Technology Co., Ltd.

2-4-8 Shinyokohama, Kouhoku-ku, Yokohama 222-8575, Japan http://www.lapis-tech.com/en/

Preface

This application note describes Connection distance measurement using the MK71521 Evaluation Kit Mini (MK71521EK1) equipped with Bluetooth® 5 compatible Bluetooth low energy module MK71521 made by Lapis Technology. The following related documents are available, so please refer to them if necessary.

- < Documents related to MK71521>
- ·MK71521 Data Sheet
- •MK715x1 Evaluation Kit Mini (MK715x1EK1) Hardware Manual

Note: In this document, MK715x1 refers to both MK71511 and MK71521.

Connection distance measurement uses the nRF5 SDK sample software Experimental: BLE Interactive Command Line Interface Example. Please refer to the related documents as necessary.

<nRF5 SDK related documents>

https://infocenter.nordicsemi.com/topic/sdk nrf5 v16.0.0/ble sdk app interactive.html

[•]Bluetooth® is a registered trademark of Bluetooth SIG, Inc.

[•]All other company and product names are the trademarks or registered trademarks of the respective companies.

Notation

Category Notation ● Value 0xnn 0bnnnn		Description		
		Represents a hexadecimal number. Represents a binary number.		
• Address	0xnnnn_nnnn	Represents a hexadecimal number. (indicates 0xnnnnnnn)		
• Unit	Word, WORD Byte, BYTE Mega, M Kilo, K Kilo, k Milli, m Micro, µ Nano, n Second, s (lowercase)	1 word = 32 bits 1 byte = 8 bits 10^6 $2^{10} = 1024$ $10^3 = 1000$ 10^{-3} 10^{-6} 10^{-9} Second		
• Term	"H" level "L" level	Indicates high voltage signal levels V_{IH} and V_{OH} as specified by the electrical characteristics. Indicates low voltage signal levels V_{IL} and V_{OL} as specified by the electrical characteristics.		

• Register Description

Read/write attribute: R indicates read-enabled; W indicates write-enabled.

MSB: Most significant bit in an 8-bit register (memory)

LSB: Least significant bit in an 8-bit register (memory)

LAPIS Technology Co.,Ltd.

Table of Contents

NOTES	i	
Preface		
Notation		
Table of Contents		
1. Measurement environment		
1.1. Overview		
1.2. Preparation (PC)	6	
1.3. Preparation (MK71521EK1)	7	
2. Measuring method	11	
3. Measurement data	17	
Revision history		

1. Measurement environment

This chapter describes the environment and preparation for connection distance measurement.

1.1. Overview

The communication distance measurement configuration and environment using MK71521EK1 is shown below.

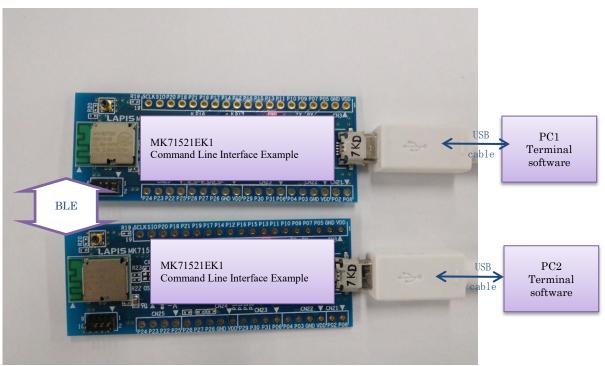


Fig.1-1 Communication distance measurement board



Fig.1-2 Communication distance measurement environment

LAPIS Technology Co., Ltd.

MK71511/MK71521 Application Note MK71521 Connection distance measurement 1. Measurement environment

1.2. Preparation (PC)

FT232RQ driver is required to connect the PC and MK71521EK1 USB connector with a USB cable. If necessary, please install the driver corresponding to your PC from the following site. http://www.ftdichip.com/Drivers/D2XX.htm

In order to write the built-in firmware from the dedicated tool, download and install the following two.
*If the download and installation procedures differ depending on the tool version, refer to the latest information for each tool.

(1) nRF5 SDK (Nordic)

Download site : https://www.nordicsemi.com/Software-and-tools/Software/nRF5-SDK

How to install : Unzip the downloaded ZIP file to any folder.

Note : Please do not use deep-paths and double-byte characters in the extracted folder.

(2) Segger Embedded Studio for ARM & J-Link Device Driver (Segger)

Download site : https://www.segger.com/downloads/embedded-studio/

How to install : Run the download file to install Segger Embedded Studio and J-Link Device Driver.

The first time you run it, follow the steps to activate.

1.3. Preparation (MK71521EK1)

Follow the steps below to write the firmware built from the source code from the IDE.

(1) Start Segger Embedded Studio

Windows operation: Start "SEGGER" → select "SEGGER Embedded Studio for ARM"

(2) Open project file

IDE operation: Open the following file from the menu "File" \rightarrow "Open Solution...".

Folder: ./<nRF5 SDK folder> /examples/ble_central_and_peripheral/experimental/ble_app_interactive/pca10040/s132/ses File: ble_app_interactive_s132_pca10040.emProject

(3) Build execution

IDE operation: Select "Build" → "Build ble_app_interactive_s132_pca10040" from the menu (Fig.1-3)

When the build is completed normally, "Build complete" is displayed in the Output window. (Fig. 1-4)

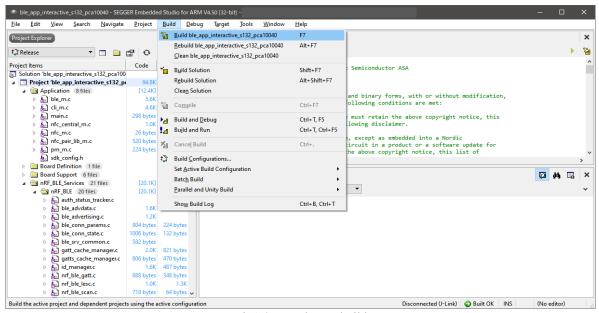


Fig1-3 Sample app build

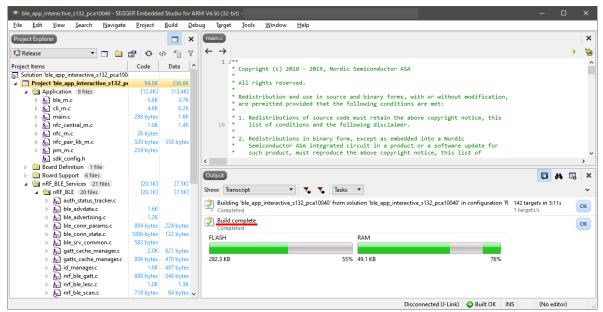


Fig.1-4 Build completed

(4) Connect J-LINK (or J-LINK lite).

Attention to the orientation of the cable (connector). The red line of the flat cable is pin 1.



Fig.1-5 J-LINK connection

(5) Erase Flash ROM

IDE operation: Select "Target" → "Connect J-Link" from the menu (Fig. 1-6)

Select "Target" → "Erase All" from the menu (Fig. 1-7)

When Flash ROM erasing is completed,

the erasing execution and time are displayed in the Output window. (Fig. 1-8)

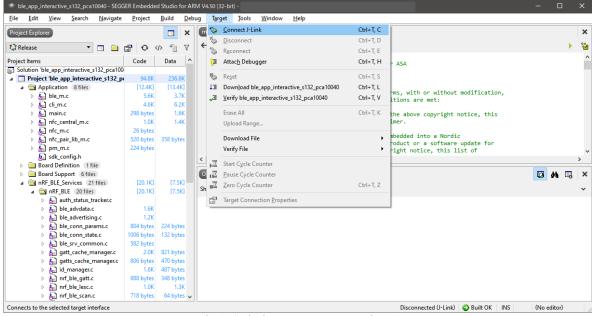


Fig.1-6 Flash ROM erase procedure 1

LAPIS Technology Co., Ltd.

MK71511/MK71521 Application Note MK71521 Connection distance measurement

1. Measurement environment

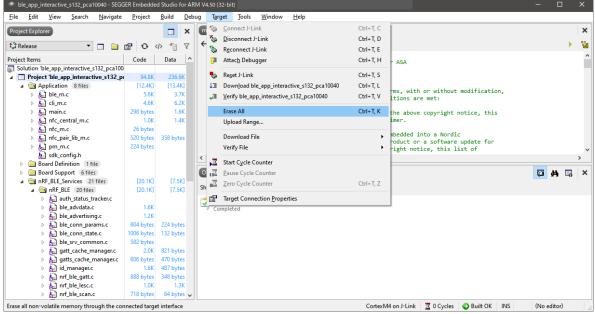


Fig. 1-7 Flash ROM erase procedure 2

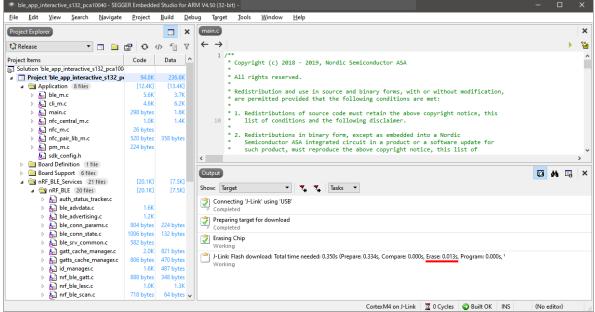


Fig. 1-8 Flash ROM erase complete

MK71511/MK71521 Application Note MK71521 Connection distance measurement 1. Measurement environment

(6) Writing the firmware

IDE operation: Select "Target" → "Download ble_app_interactive_s132_pca10040" (Fig. 1-9)

When writing the firmware is completed, the result is displayed in the Output window. (Fig. 1-10)

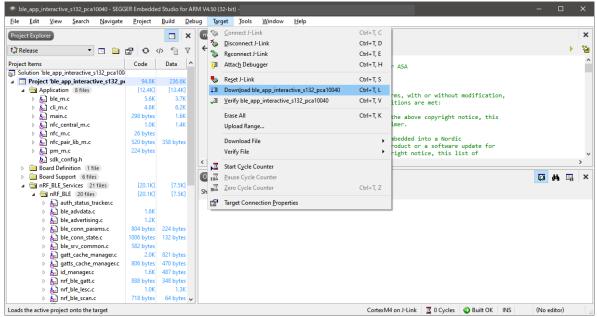


Fig. 1-9 Writing the firmware

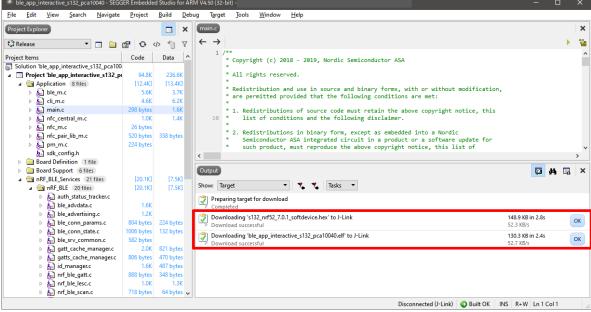


Fig. 1-10 Writing the firmware is complete

- (7) Write application code on another MK71521EK1 for communication test.
- (8) Segger Embedded Studio end Select the menu "File" → "Exit" or click the "×" on the upper right of the tool to exit the tool.

2. Measuring method

This chapter describes how to use the sample software.

The sample software (BLE Interactive Command Line Interface Example) can establish connection between devices by command control.

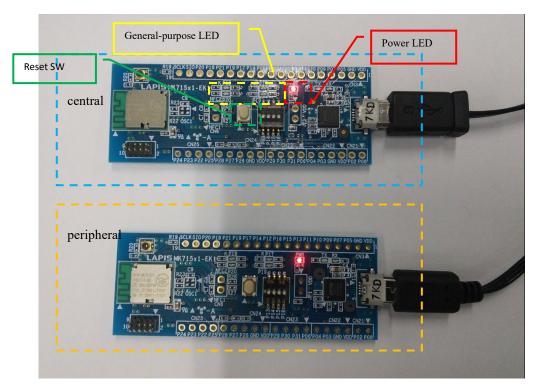


Fig. 2-1 Connection distance measurement board

(1) Connect MK71521EK1 to PC with USB cable. (Fig. 2-1) Power LED lights on

(2) Start the terminal software such as TeraTerm and set the serial port.

Port: Your COM port number Baud rate: 115,200 bps

Data: 8bit Parity: None Stop: 1 bit

Flow control: None

(3) Push the Reset SW(central/peripheral)

Start of the sample software is displayed on the terminal software (Fig. 2-2). The command is displayed by pressing the "tab" key (Fig. 2-2).

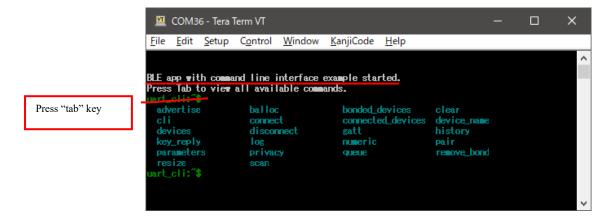


Fig. 2-2 Starting the sample software

(4) Peripheral: Input the command "advertise on" and press ENTER. Advertisement is executed (Fig. 2-3) LED3 lights on. (Fig. 2-4)



Fig. 2-3 Executing adverise



Fig.2-4 Advertisement execution LED

(5) Central: Input the command "scan on" and press ENTER. The scan will be performed. (Fig. 2-5) LED1 lights on (Fig. 2-6)

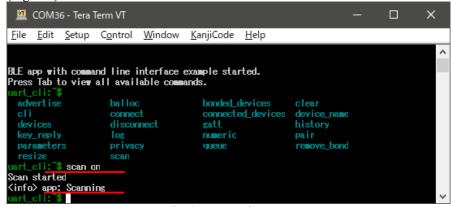


Fig. 2-5 Executing scan



Fig. 2-6 Scan execution LED

MK71511/MK71521 Application Note MK71521 Connection distance measurement 2. Measuring method

(6) Central: Enter the command "devices" and press ENTER.

The detected device address/device name is displayed. (Fig. 2-7)

The device name "Nordic~" is the peripheral device.

(DEVICE NAME on the sample program is "Nordic ble interactive")

If there are many Bluetooth devices in the vicinity, the peripheral device may not be displayed,

It may be displayed by entering "devices" again.

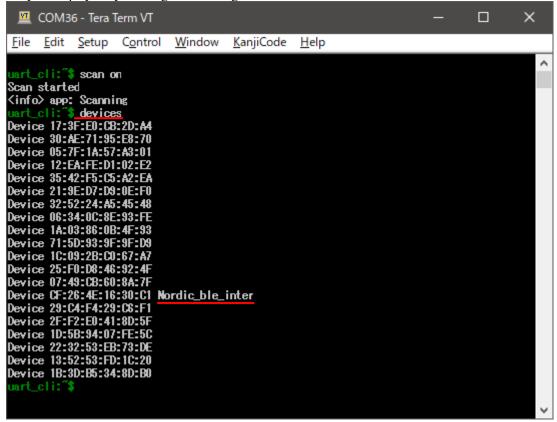


Fig. 2-7 Scan execution result display

(7) central: Enter the command "connect peripheral address" and press ENTER (Fig. 2-8) LED4 lights on when connection is complete.

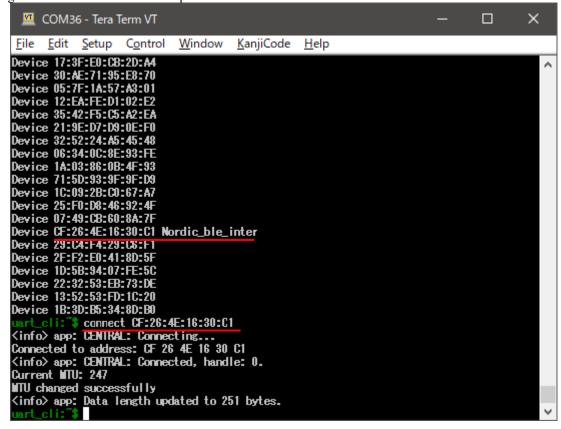


Fig. 2-8 Connection established (central)

LED2 lights on the peripheral side when the connection is completed. (Fig. 2-10)



Fig. 2-9 Connection establishment (peripheral)

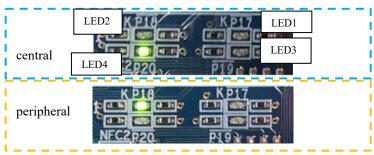


Fig. 2-10 LED display for establishing connection

MK71511/MK71521 Application Note MK71521 Connection distance measurement 2. Measuring method

The parameters for connection are as follows. (Default value of sample software)

C.I : 500msec S.L : 5

T.O: 6200msec PHY: 1M

Each parameter can be changed by command. (Not changed in this test)

After entering the command "parameters", press the tab key to display command candidates (Fig. 2-11)

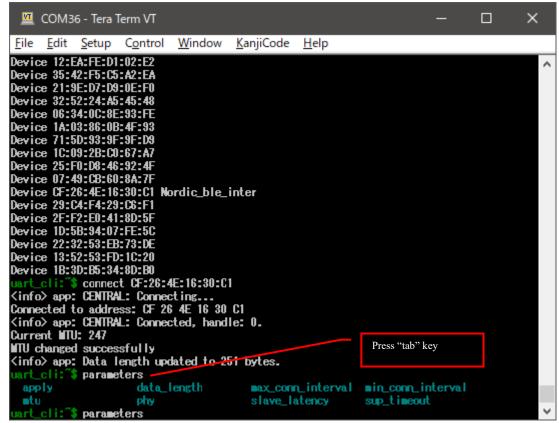


Fig. 2-11 Parameter setting command

MK71511/MK71521 Application Note MK71521 Connection distance measurement 2. Measuring method

(8) After connecting, make sure that you do not receive disconnection notification due to timeout etc. for a certain period of time. Issue a disconnect request (command "disconnect peripheral address") to confirm that the connection can be completed normally. (Fig. 2-12, 2-13)

reason 0x8: CONNECTION TIMEOUT reason 0x13: REMOTE USER TERMINATED CONNECTION reason 0x16: CONNECTION TERMINATED BY LOCAL HOST After disconnection, the peripheral side resumes sending advertise.

```
COM36 - Tera Term VT
                                                                                       Window
                                         <u>K</u>anjiCode
      <u>E</u>dit
            <u>S</u>etup
                     Control
                                                      <u>H</u>elp
Device 07:49:CB:60:8A:7F
Device CF:26:4E:16:30:C1 Nordic_ble_inter
Device 29:C4:F4:29:C6:F1
Device 2F:F2:E0:41:8D:5F
Device 10:5B:94:07:FE:5C
Device 22:32:53:EB:73:DE
Device 13:52:53:FD:1C:20
Device 1B:3D:B5:34:8D:B0
       i: $ cannect CF:26:4E:16:30:C1
⟨info⟩ app: CENTRAL: Connecting.
Connected to address: CF 26 4E 16 30 C1
<info> app: CENTRAL: Connected, handle: 0.
Current MTV: 247
MTU changed successfully
<info> app: Data length updated to 251 bytes.
 mrt_cli:~$ parameters
  apply
                       data_length
                                            max_conn_interval min_conn_interval
  mtu
                       phy
                                            slave_latency
                                                                  sup_timeout
 art_cli:"$
  advertise
                       balloc
                                            bonded_devices
                                                                 clear
                       connect
                                            connected_devices
                                                                 device_name
  devices
                       disconnect
                                            gatt
                                                                 history
  key_reply
                       log
                                            numeric
                                                                 pair
  parameters
                       privacy
                                            queue
                                                                  remove bond
  resize
             disconnect CF:26:4E:16:30:C1
⟨info⟩ app: CENTRAL: Disconnected, handle: 0, reason: 0x16
```

Fig. 2-12 Disconnection display (central)

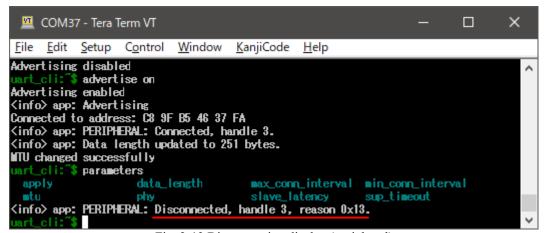


Fig. 2-13 Disconnection display (peripheral)

(9) Change the distance between central/peripheral and repeat steps ⑤ to check the connectable distance.

3. Measurement data

The connection distance measurement data of MK71521EK1 is shown below.

	Distance (m)	
Connection distance (Maintain connection)	95	
Detection distance	150	

^{*} The communication distance changes depending on the measurement environment. It does not guarantee communication performance.

Connection maintenance confirmation time: 1 min Equipment orientation: Z-Plane-0° facing (Fig. 3-1)

Equipment height: 1.5m (Fig. 3-2)



Fig.3-1 Equipment direction during measurement

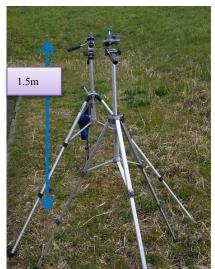


Fig.3-2 Height of equipment during measurement

Revision history

	Issue date	Page		
Document No.		Before revision	After revision	Remarks
FEXK715x1_AN_Distance-01	Oct. 16, 2020	_	_	First edition